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By: May Beyma  
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**IN THE UNITED STATES PATENT AND  
TRADEMARK OFFICE**

Applicant: EMESH, Ismail et al      Docket No.: 34759.9600  
Serial No.: 09/781,593      Art Unit: 3723  
Filing Date: 2/12/2001      Examiner: Unknown  
TITLE: METHOD AND APPARATUS FOR ELECTROCHEMICAL PLANARIZATION  
OF A WORKPIECE

10/19/2001 SZEWDIE1 00000002 09781593

01 FC:102  
02 FC:103

252.00 OP  
144.00 OP

**PRELIMINARY AMENDMENT**

Assistant Commissioner  
for Patents  
Box AMENDMENT-FEE  
Washington, D.C. 20231

Dear Madam or Sir:

10/17/2001 SZEWDIE1 00000004 09781593

01 FC:102  
02 FC:103

Adjustment date: 10/19/2001 SZEWDIE1  
10/17/2001 SZEWDIE1 00000004 09781593

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02 FC:103

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**TC 1700**

Prior to the examination of the above-identified application, please enter the following amendments:

**IN THE SPECIFICATION**

Please replace the paragraph beginning at page 8, line 24, with the following rewritten paragraph:

--The electrolytic planarizing solution may also include a film forming agent which includes any compound or mixture of compounds that facilitates the formation of a passivation film of metal oxides and dissolution-inhibiting layers on the metallized surface of wafer 60. The passivation film reduces, and preferably eliminates, wet etching of the low topography areas of the metallized surface 80 of wafer 60 until the low topography areas come in contact with polishing pad 40. When these low topography areas come in contact with polishing pad 40 and electrical conductors 70, described below, the passivation film is removed and electrochemical etching may proceed. Thus, the passivation film enhances uniform planarization of wafer 60. Suitable film forming agents may be formed of nitrogen-containing cyclic compounds such as proline, adedine, mercaptonitriles, imidazole, triazole, quinaldic acid, benzotriazole,